Reliability Data

ON Semiconductor

Die Related Grand Summary Data

Activation Energy	0.7	*electron-volts*
Die Junction Temperature	55	*Celsius*
One-sided Upper Confidence Level	90	*percent*

PRODUCT TECHNOLOGY	LOTS	REJ	SS	DEVICE-HOURS	EQUIVALENT DEVICE-HOURS	FITS
ACMOS	54	0	7,816	3,381,568	282,269,282	8.2
BP STD LINEAR	294	1	25,023	10,269,782	1,691,310,665	2.3
BPT	169	0	10,456	4,208,028	1,056,009,285	2.2
CMOS STD	156	0	12,100	4,936,608	1,024,306,361	2.2
CMOS SUB	80	0	8,498	4,494,308	876,508,783	2.6
EG BP LINEAR	460	0	60,627	28,711,072	2,286,429,603	1.0
MOSAIC1/1.5	18	0	1,285	628,082	164,121,502	14.0
MOSAIC3	57	4	4,449	3,891,038	1,012,742,604	7.9
MOSAIC5	66	0	4,574	3,834,296	997,263,815	2.3
PWR SENSE	142	10	49,939	9,985,572	1,064,996,705	14.5
RECT	488	40	30,421	10,174,964	4,805,989,086	10.3
SiGe	13	0	1,278	724,248	236,394,610	9.7
SSD	41	0	3,022	1,481,200	384,087,657	6.0
SST	239	0	14,893	3,660,104	949,095,848	2.4
THYRISTOR	323	1	17,620	3,536,392	685,345,982	5.7
TMOS HD	205	3	15,533	12,969,824	3,560,940,180	1.9
TMOS IGBT	27	0	1,539	706,120	183,102,874	12.6
TMOS STD	201	2	14,140	9,762,752	3,491,749,121	1.5
VHVIC	114	7	11,303	6,569,592	521,307,172	22.6
ZENER	301	0	18,599	6,489,224	1,661,427,872	1.4